

# LQH43NH4R7J03L Datasheet



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DiGi Electronics Part Number	LQH43NH4R7J03L-DG
Manufacturer	<a href="#">Murata Electronics</a>
Manufacturer Product Number	LQH43NH4R7J03L
Description	FIXED IND 4.7UH 750MA 108MOHM SM
Detailed Description	4.7 $\mu$ H Unshielded Drum Core, Wirewound Inductor 750 mA 108mOhm Max 1812 (4532 Metric)



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## Purchase and inquiry

**Manufacturer Product Number:**

LQH43NH4R7J03L

**Series:**

LQH43

**Type:**

Drum Core, Wirewound

**Inductance:**4.7  $\mu$ H**Current Rating (Amps):**

750 mA

**Shielding:**

Unshielded

**Q @ Freq:**

20 @ 1MHz

**Ratings:**

AEC-Q200

**Inductance Frequency - Test:**

1 MHz

**Mounting Type:**

Surface Mount

**Supplier Device Package:**

1812

**Height - Seated (Max):**

0.110" (2.80mm)

**Manufacturer:**

Murata Electronics

**Product Status:**

Discontinued at Digi-Key

**Material - Core:**

Ferrite

**Tolerance:** $\pm$ 5%**Current - Saturation (Isat):**

-

**DC Resistance (DCR):**

108mOhm Max

**Frequency - Self Resonant:**

38MHz

**Operating Temperature:**

-40°C ~ 125°C

**Features:**

-

**Package / Case:**

1812 (4532 Metric)

**Size / Dimension:**

0.177" L x 0.126" W (4.50mm x 3.20mm)

**Base Product Number:**

LQH43NH

## Environmental & Export classification

**RoHS Status:**

ROHS3 Compliant

**REACH Status:**

REACH Unaffected

**HTSUS:**

8504.50.8000

**Moisture Sensitivity Level (MSL):**

1 (Unlimited)

**ECCN:**

EAR99

# Reference Only

Spec No. JELF243A-9150B-01

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**CHIP COIL (CHIP INDUCTORS) LQH43NH□□□□03L**  
**Murata Standard Reference Specification [AEC-Q200]**
**1.Scope**

This reference specification applies to LQH43NH series, Chip coil (Chip Inductors) for automotive Electronics based on AEC-Q200 .

**2.Part Numbering**

(ex)   LQ     H     43     N     H     1R0     M     0     3     L    
 Product ID Structure Dimension Applications Category Inductance Tolerance Features Electrode Packaging  
 (L×W) and Characteristics L:Taping

**3.Rating**

- Operating Temperature Range.      -40 °C to +125 °C
- Storage Temperature Range.       -40 °C to +125 °C

Customer's Part Number	MURATA Part Number	Inductance		Q (min.)	DC Resistance		Self Resonant Frequency (MHz min)	*1:Rated Current (mA)	ESD 5A: 8kV
		(μH)	Tolerance (%)		(Ω)	Tolerance (%)			
	LQH43NH1R0M03L	1.0	M: ±20	20	0.033	±20	120	1300	5A
	LQH43NH1R2K03L	1.2	K: ±10		0.043				
	LQH43NH1R5J03L	1.5	J: ±5		0.049				
	LQH43NH1R8J03L	1.8			0.043				
	LQH43NH2R2J03L	2.2			0.049				
	LQH43NH2R7J03L	2.7			0.053				
	LQH43NH3R3J03L	3.3			0.077				
	LQH43NH3R9J03L	3.9			0.12				
	LQH43NH4R7J03L	4.7			0.090				
	LQH43NH5R6J03L	5.6			25		0.11		
	LQH43NH6R8J03L	6.8		30	0.18				
	LQH43NH8R2J03L	8.2			0.18				
	LQH43NH100J03L	10	35	0.20					
	LQH43NH120J03L	12		0.25					
	LQH43NH150J03L	15		0.30					
	LQH43NH180J03L	18		0.35					
	LQH43NH220J03L	22		0.47					
	LQH43NH270J03L	27		0.60					
	LQH43NH330J03L	33		0.70					
	LQH43NH390J03L	39		0.80					
	LQH43NH470J03L	47		0.87					
	LQH43NH560J03L	56		1.34					
	LQH43NH680J03L	68	1.52						
	LQH43NH820J03L	82	1.70						
	LQH43NH101J03L	100	40	2.00					
	LQH43NH121J03L	120		2.60					
	LQH43NH151J03L	150		3.00					

Customer's Part Number	MURATA Part Number	Inductance		Q (min.)	DC Resistance		Self Resonant Frequency (MHz min)	*1:Rated Current (mA)	ESD 5A: 8kV
		( $\mu$ H)	Tolerance (%)		( $\Omega$ )	Tolerance (%)			
	LQH43NH181J03L	180	J: $\pm$ 5	40	3.40	$\pm$ 20	5.0	110	5A
	LQH43NH221J03L	220			3.80		4.5		
	LQH43NH271J03L	270			5.50		4.0		
	LQH43NH331J03L	330			6.20		3.6		
	LQH43NH391J03L	390			6.90		3.3		
	LQH43NH471J03L	470			7.80		3.0		
	LQH43NH561J03L	560			11.3		2.7		
	LQH43NH681J03L	680			12.9		2.5		
	LQH43NH821J03L	820			14.5		2.2		
	LQH43NH102J03L	1000			15.5		2.0		
	LQH43NH122J03L	1200			20.3		1.8		
	LQH43NH152J03L	1500			23.7		1.6		
	LQH43NH182J03L	1800			26.7		1.5		
	LQH43NH222J03L	2200			30.6		1.3		

\*1:When applied Rated current to the Products, self temperature rise shall be limited to 20°C max and Inductance will be within  $\pm$ 10% of nominal value.

#### 4. Testing Conditions

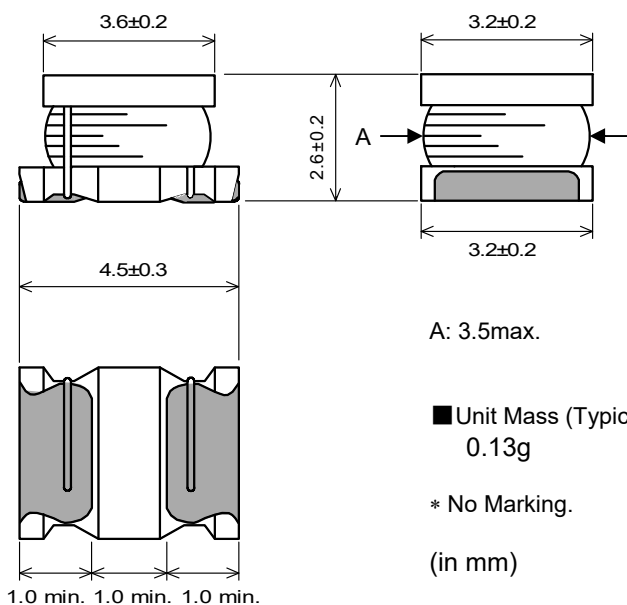
《Unless otherwise specified》

Temperature : Ordinary Temperature / 15°C to 35°C  
Humidity : Ordinary Humidity / 25%(RH) to 85%(RH)

《In case of doubt》

Temperature : 20  $\pm$  2°C  
Humidity : 60%(RH) to 70%(RH)  
Atmospheric Pressure : 86kPa to 106 kPa

#### 5.Appearance and Dimensions (No marking)



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## 6. Electrical Performance

No.	Item	Specification	Test Method
6.1	Inductance	Inductance shall meet item 3.	Measuring Equipment: KEYSIGHT 4192A or equivalent Measuring Frequency: 1MHz / 1.0 to 390 $\mu$ H 1kHz / 470 to 2200 $\mu$ H
6.2	Q	Q shall meet item 3.	Measuring Equipment: KEYSIGHT 4192A or equivalent Measuring Frequency: 1MHz / 1.0 to 82 $\mu$ H 796kHz / 100 to 820 $\mu$ H 252kHz / 1000 to 2200 $\mu$ H
6.3	DC Resistance	DC Resistance shall meet item 3.	Measuring Equipment: Digital multi meter
6.4	Self Resonant Frequency(S.R.F)	S.R.F shall meet item 3.	Measuring Equipment: KEYSIGHT E4991A or equivalent

## 7. AEC-Q200 Requirement

### 7.1 Performance (based on Table 5 for Magnetics(Inductors / Transformer)

AEC-Q200 Rev.D issued June. 1 2010

AEC-Q200			Murata Specification / Deviation				
No	Stress	Test Method					
3	High Temperature Exposure	1000hours at 125 deg C Set for 24hours at room temperature, then measured.	Meet Table A after testing. Table A <table border="1" style="margin-left: 20px;"> <tr> <td>Appearance</td> <td>No damage</td> </tr> <tr> <td>Inductance change</td> <td>Within <math>\pm 10\%</math></td> </tr> </table>	Appearance	No damage	Inductance change	Within $\pm 10\%$
Appearance	No damage						
Inductance change	Within $\pm 10\%$						
4	Temperature Cycling	1000cycles -40 deg C to + 125 deg C Set for 24hours at room temperature, then measured.	Meet Table A after testing.				
7	Biased Humidity	1000hours at 85 deg C, 85%RH unpowered.	Meet Table A after testing.				
8	Operational Life	Apply 125 deg C 1000 hours Set for 24hours at room temperature, then measured	Meet Table A after testing.				
9	External Visual	Visual inspection	No abnormalities				
10	Physical Dimension	Meet ITEM 5 (Appearance and Dimensions)	No defects				
12	Resistance to Solvents	Per MIL-STD-202 Method 215	Not Applicable				
13	Mechanical Shock	Per MIL-STD-202 Method 213 100g's/6ms/Half sine	Meet Table A after testing.				
14	Vibration	5g's for 20 minutes, 12cycles eah of 3 orientations Test from 10-2000Hz. 12cycles each of 3 orientations	Meet Table A after testing.				
15	Resistance to Soldering Heat	No-heating Solder temperature 260C+/-5 deg C Immersion time 10s	Meet Table A after testing.				
17	ESD	Per AEC-Q200-002	Meet Item 3 (Rating) No defects				
18	Solderbility	Per J-STD-002	Method B : Not Applicable 95% of the terminations is to be soldered. (Except exposed wire)				
19	Electrical Characterization	Measured : Inductance	No defects				

# Reference Only

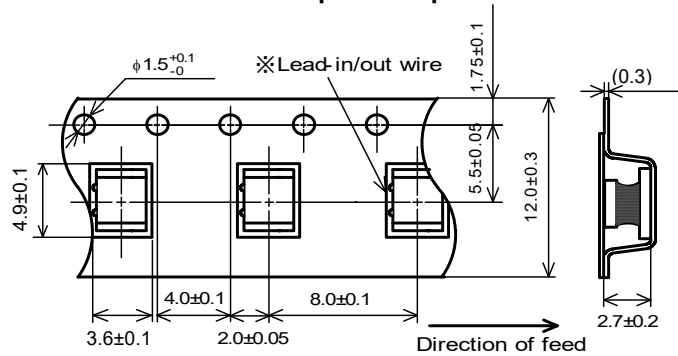
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AEC-Q200			Murata Specification / Deviation				
No	Stress	Test Method					
20	Flammability	Per UL-94	Not Applicable				
21	Board Flex	Epoxy-PCB(1.6mm) Deflection 2mm(min) 60s minimum holding time	Murata deviation request: 5s Meet Table B after testing. <u>Table B</u> <table border="1" style="margin-left: 20px;"> <tr> <td>Appearance</td> <td>No damage</td> </tr> <tr> <td>DC resistance change</td> <td>Within <math>\pm 10\%</math></td> </tr> </table>	Appearance	No damage	DC resistance change	Within $\pm 10\%$
Appearance	No damage						
DC resistance change	Within $\pm 10\%$						
22	Terminal Strength	Per AEC-Q200-006 A force of 17.7N for 60s	No defects				

## 8. Specification of Packaging

### 8.1 Appearance and Dimensions of plastic tape



※The packing directions of the chip coil in taping are unified with the in/out positions of the lead wire.

Dimension of the Cavity is measured at the bottom side.

### 8.2 Specification of Taping

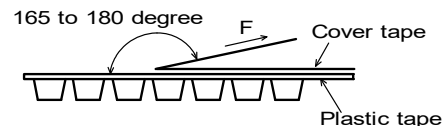
- (1) Packing quantity (standard quantity)  
500 pcs / reel
- (2) Packing Method  
Products shall be packed in the each embossed cavity of plastic tape and sealed by cover tape.
- (3) Sprocket hole  
The sprocket holes are to the right as the tape is pulled toward the user.
- (4) Spliced point  
Plastic tape and Cover tape has no spliced point.
- (5) Missing components number  
Missing components number within 0.025 % of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

### 8.3 Pull Strength

Plastic tape	10N min.
Cover tape	5N min.

### 8.4 Peeling off force of cover tape

Speed of Peeling off	300mm / min
Peeling off force	0.2N to 0.7N (minimum value is typical)



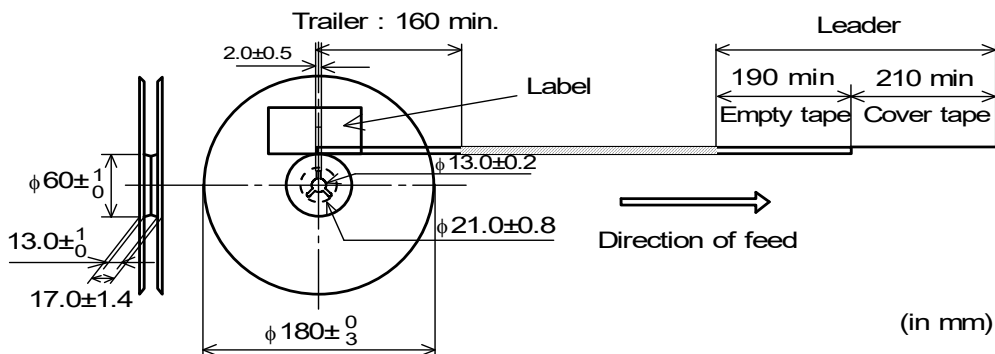
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### 8.5 Dimensions of Leader-tape, Trailer and Reel

There shall be leader-tape (cover tape) and trailer-tape (empty tape) as follows.



### 8.6 Marking for reel

Customer part number, MURATA part number, Inspection number(\*1), RoHS marking(\*2), Quantity etc ...

\*1) <Expression of Inspection No.> □□ OOOO xxx  
 (1) (2) (3)

(1) Factory Code

(2) Date                      First digit                      : Year / Last digit of year  
 Second digit                      : Month / Jan. to Sep. → 1 to 9, Oct. to Dec. → O, N, D  
 Third, Fourth digit                      : Day

(3) Serial No.

\*2) « Expression of RoHS marking »      ROHS – Y (Δ)  
 (1) (2)

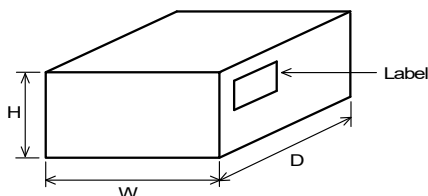
(1) RoHS regulation conformity

(2) MURATA classification number

### 8.7 Marking for Outside package (corrugated paper box)

Customer name, Purchasing order number, Customer part number, MURATA part number, RoHS marking (\*2), Quantity, etc ...

### 8.8. Specification of Outer Case



Outer Case Dimensions (mm)			Standard Reel Quantity in Outer Case (Reel)
W	D	H	
186	186	93	5

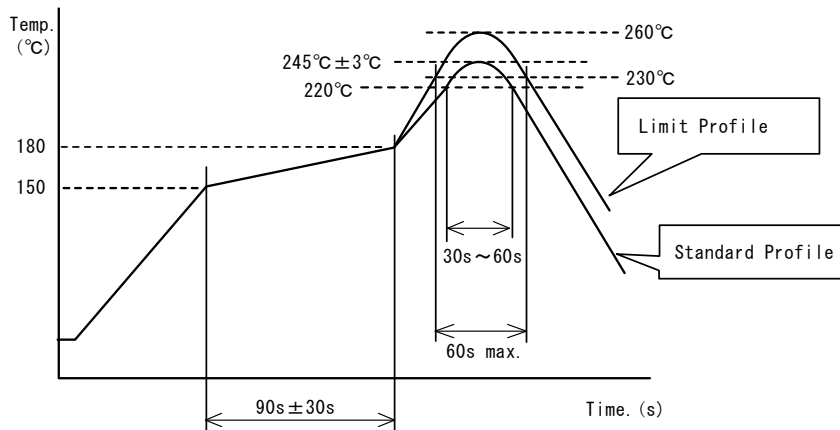
\*Above Outer Case size is typical. It depends on a quantity of an order





**10.3 Reflow soldering conditions**

- Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150°C max. Cooling into solvent after soldering also should be in such a way that the temperature difference is limited to 100°C max.  
Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of products quality.
- Standard soldering profile and the limit soldering profile is as follows.  
The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.
- Reflow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150~180°C、90s±30s	
Heating	above 220°C、30s~60s	above 230°C、60s max.
Peak temperature	245±3°C	260°C,10s
Cycle of reflow	2 times	2time

**10.4 Reworking with soldering iron.**

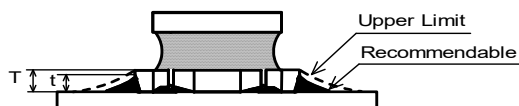
The following conditions must be strictly followed when using a soldering iron.

Pre-heating	150°C,1 min
Tip temperature	350°C max.
Soldering iron output	80W max.
Tip diameter	φ 3mm max.
Soldering time	3(+1,-0)s
Times	2 times

Note : Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the products due to the thermal shock.

**10.5 Solder Volume**

- Solder shall be used not to be exceeded the upper limits as shown below.
- Accordingly increasing the solder volume, the mechanical stress to Chip is also increased.  
Exceeding solder volume may cause the failure of mechanical or electrical performance.



$$\frac{1}{3}T \leq t \leq T$$

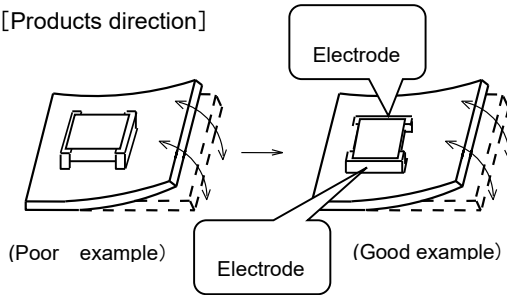
T: Lower flange thickness

## 10.6 Product's location

The following shall be considered when designing and laying out P.C.B.'s.

- (1) P.C.B. shall be designed so that products are not subject to the mechanical stress due to warping the board.

[Products direction]



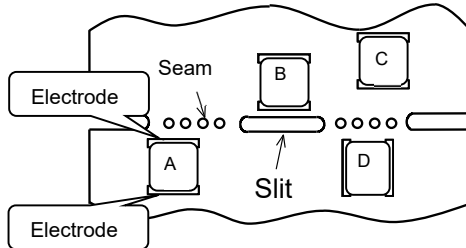
The electrode part of the products should be located like the picture to the mechanical stress.

- (2) Components location on P.C.B. separation.

It is effective to implement the following measures, to reduce stress in separating the board.

It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

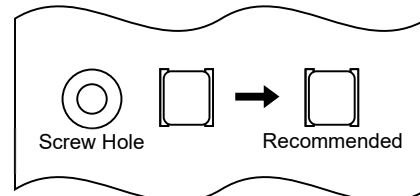
Contents of Measures	Stress Level
(1) Turn the mounting direction of the component parallel to the board separation surface.	A > D *1
(2) Add slits in the board separation part.	A > B
(3) Keep the mounting position of the component away from the board separation surface.	A > C



\*1 A > D is valid when stress is added vertically to the perforation as with Hand Separation. If a Cutting Disc is used, stress will be diagonal to the PCB, therefore A > D is invalid.

- (3) Mounting Components Near Screw Holes

When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw. Mount the component in a position as far away from the screw holes as possible.



## 10.7 Cleaning Conditions

Products shall be cleaned on the following conditions.

- (1) Cleaning temperature shall be limited to 60°C max. (40°C max for alcohol type cleaner.)
- (2) Ultrasonic cleaning shall comply with the following conditions with avoiding the resonance phenomenon at the mounted products and P.C.B.  
Power : 20 W / l max.    Frequency : 28kHz to 40kHz    Time : 5 min max.
- (3) Cleaner
  1. Alternative cleaner
    - Isopropyl alcohol (IPA)
  2. Aqueous agent
    - PINE ALPHA ST-100S
- (4) There shall be no residual flux and residual cleaner after cleaning.  
In the case of using aqueous agent, products shall be dried completely after rinse with de-ionized water in order to remove the cleaner.
- (5) Other cleaning  
Please contact us.

**10.8 Resin coating (moistureproof coating)**

Do not make any resin coating.

The inductance value may change due to high cure-stress of resin to be used for coating/molding products. An open circuit issue may occur by mechanical stress caused by the resin, amount/cured shape of resin, or operating condition etc. Some resin contains some impurities or chloride possible to generate chlorine by hydrolysis under some operating condition may cause corrosion of wire of coil, leading to open circuit.

**10.9 Caution for use**

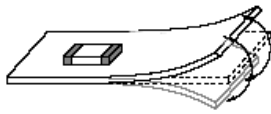
- Sharp material such as a pair of tweezers or other material such as bristles of cleaning brush, shall not be touched to the winding portion to prevent the breaking of wire.
- Mechanical shock should not be applied to the products mounted on the board to prevent the breaking of the core

**10.10 Handling of a substrate**

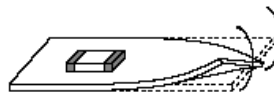
After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.

Excessive mechanical stress may cause cracking in the product.

Bending



Twisting

**10.11 Storage and Handling Requirements****(1) Storage period**

Use the products within 12 months after delivered.

Solderability should be checked if this period is exceeded.

**(2) Storage conditions**

- Products should be stored in the warehouse on the following conditions.

Temperature : -10 °C to 40 °C

Humidity : 15 % to 85 % relative humidity No rapid change on temperature and humidity

The electrode of the products is coated with solder. Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.

- Products should not be stored on bulk packaging condition to prevent the chipping of the core and the breaking of winding wire caused by the collision between the products.
- Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
- Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.

**(3) Handling Condition**

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

**11.  Note**

- (1) Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2) You are requested not to use our product deviating from the agreed specifications.
- (3) The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering.

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